

**METHOD, SYSTEM, AND APPARATUS FOR**  
**EMBEDDING CIRCUITS**

**Abstract of the Invention**

5       A method, system, and apparatus for embedding circuits. The present invention allows reduction in the size of fabricated multichip modules by embedding circuitry within a substrate. A first layer of dielectric material is provided and a circuit having a predetermined length, width, and depth is provided. Then, a cavity is formed in the first layer of dielectric material substantially corresponding to the predetermined length and  
10      width of the circuit. After the cavity is formed, the circuit is deposited into the cavity. Once the circuit is deposited, a second layer of dielectric material may be provided to cover the circuit.